Docket No.: 51876P542

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re the Application of:

TAE-WOO JUNG, ET AL.

Application No.:

Filed:

For: METHOD FOR FABRICATING

SEMICONDUCTOR DEVICE HAVING

TRENCH TYPE DEVICE ISOLATION LAYER

Art Group:

Examiner:

## INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure, enclosed is a copy of Information Disclosure Statement by Applicant (form PTO/SB/08), which is being submitted concurrently with the Utility Application. It is respectfully requested that the cited references be considered and that the enclosed copy of PTO/SB/08 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s).

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The submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made in the subject application and is not to be construed as an admission that the information cited in this statement is material to patentability.

Please charge any fees due to Deposit Account 02-2666. A duplicate copy of the Fee Transmittal (PTO/SB/17) is enclosed for this purpose.

Respectfully submitted,

BLAKELY, SOKOLOFI, TAYLOR & ZAFMAN LLP

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Date: December 30, 2003

-2-51876P542

Substitute for form 1449A/PTO				Complete if Known		
			CUDE	Application Number		
INFORMATION DISCLOSURE				Filing Date		
STATEMENT BY APPLICANT			ICANT	First Named Inventor	Tae-Woo JUNG	
(use as many sheets as necessary)				Art Unit		
(use as many sheets us necessary)				Examiner Name		
Sheet	1	of	1	Attorney Docket Number	51876P542	

U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No.¹	Document Number  Number - Kind Code <sup>2</sup> (if known)	Publication Date or Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
		US-6,444,540 B2	09-03-2002	Kawada et al.		
		US-6,500,727 B1	12-31-2002	Chen et al.		
		US-6,218,309 B1	04-17-2001	Miller et al.		
		US-6,579,801 B1	06-17-2003	Dakshina-Murthy et al.		
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FOREIGN PATENT DOCUMENTS						
	Cite	Foreign Patent Document			Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	т
	No.1	Country Code <sup>3</sup> - Number <sup>4</sup> - Kind Code <sup>5</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document		To
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Signature	Considered	

Based on PTO/SB/08A (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wlr) 08/11/2003.

<sup>\*</sup>Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

<sup>&</sup>lt;sup>1</sup>Applicant's unique citation designation number (optional). <sup>2</sup>See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached.

## **Information Disclosure Statement**

New U.S. Patent Application for METHOD FOR FABRICATING SEMICONDUCTOR DEVICE HAVING TRENCH TYPE DEVICE ISOLATION LAYER Our Ref. No.: P03H3019/US/cj

## Reference No.:

- (1) US Patent No. 6,444,540
- (2) US Patent No. 6,500,727
- (3) US Patent No. 6,218,309
- (4) US Patent No. 6,579,801